CLAIMS

What is claimed is:

1. An apparatus comprising:
a coreless substrate strip;
a plurality of solder balls attached to a backside of the coreless substrate strip; and
a backside stiffening mold amongst the solder balls.

2. The apparatus of claim 1, wherein the backside stiffening mold comprises a height of about 200 micrometers.

3. The apparatus of claim 1, wherein the coreless substrate strip comprises a height of about 200 micrometers.

4. The apparatus of claim 3, further comprising an integrated circuit device attached to a topside of the coreless substrate strip.

5. An apparatus comprising:
a laser laminated substrate strip;
a plurality of solder balls attached to a backside of the laser laminated substrate strip;
a backside stiffening mold amongst the solder balls; and
an integrated circuit device attached to a topside of the laser laminated substrate strip.

6. The apparatus of claim 5, wherein the backside stiffening mold comprises a height of about 200 micrometers.

7. The apparatus of claim 5, wherein the laser laminated substrate strip comprises a height of about 200 micrometers.

8. The apparatus of claim 5, wherein the solder balls comprise a diameter of about 10 mils.

9. The apparatus of claim 5, further comprising a second integrated circuit device attached to the topside of the laser laminated substrate strip.

10. An apparatus comprising:

a coreless substrate strip, including topside contacts adapted for attachment to an integrated circuit device, and backside contacts formed at a pitch larger than the topside contacts;

a plurality of solder balls attached to a backside of the coreless substrate strip;

a backside stiffening mold amongst the solder balls; and

a second substrate attached above the coreless substrate strip.

11. The apparatus of claim 10, further comprising an integrated circuit device attached to the topside contacts.

12. The apparatus of claim 10, wherein the second substrate includes a coreless substrate strip.

13. The apparatus of claim 10, further comprising a second integrated circuit device attached to a top surface of the second substrate.

14. An apparatus comprising:

a laser laminated substrate strip, including topside contacts adapted for attachment to an integrated circuit device, and backside contacts formed at a pitch larger than the topside contacts;

a plurality of solder balls attached to a backside of the laser laminated substrate strip;

a backside stiffening mold amongst the solder balls; and

an integrated circuit device attached to a topside of the laser laminated substrate strip.

15. The apparatus of claim 14, wherein the backside stiffening mold comprises a height of about 200 micrometers.

16. The apparatus of claim 14, wherein the laser laminated substrate strip comprises a height of about 200 micrometers.

17. The apparatus of claim 14, wherein the solder balls comprise a diameter of about 10 mils.

What is claimed is:

1. An apparatus comprising:

a coreless substrate strip;

a plurality of solder balls attached to a backside of the coreless substrate strip;

a backside stiffening mold amongst the solder balls;

an integrated circuit device attached to a topside of the coreless substrate strip; and

a second substrate attached above the integrated circuit device and the coreless substrate strip.

2. The apparatus of claim 1, wherein the backside stiffening mold comprises a height of about 200 micrometers.

3. The apparatus of claim 1, wherein the coreless substrate strip comprises a height of about 200 micrometers.

4. The apparatus of claim 3, further comprising an integrated circuit device attached to a topside of the coreless substrate strip.

5. An apparatus comprising:

a laser laminated substrate strip;

a plurality of solder balls attached to a backside of the laser laminated substrate strip;

a backside stiffening mold amongst the solder balls;

an integrated circuit device attached to a topside of the laser laminated substrate strip; and

a second integrated circuit device attached to the topside of the laser laminated substrate strip.

6. The apparatus of claim 5, wherein the backside stiffening mold comprises a height of about 200 micrometers.

7. The apparatus of claim 5, wherein the laser laminated substrate strip comprises a height of about 200 micrometers.

8. The apparatus of claim 5, wherein the solder balls comprise a diameter of about 10 mils.

9. An apparatus comprising:

a coreless substrate strip, including topside contacts adapted for attachment to an integrated circuit device, and backside contacts formed at a pitch larger than the topside contacts;

a plurality of solder balls attached to a backside of the coreless substrate strip;

a backside stiffening mold amongst the solder balls; and

an integrated circuit device attached to a topside of the coreless substrate strip; and

a second substrate attached above the integrated circuit device and the coreless substrate strip.

10. The apparatus of claim 9, further comprising an integrated circuit device attached to the topside contacts.

11. The apparatus of claim 9, wherein the second substrate includes a coreless substrate strip.

12. The apparatus of claim 9, further comprising a second integrated circuit device attached to a top surface of the second substrate.

13. An apparatus comprising:

a laser laminated substrate strip, including topside contacts adapted for attachment to an integrated circuit device, and backside contacts formed at a pitch larger than the topside contacts;

a plurality of solder balls attached to a backside of the laser laminated substrate strip;

a backside stiffening mold amongst the solder balls;

an integrated circuit device attached to a topside of the laser laminated substrate strip; and

a second integrated circuit device attached to the topside of the laser laminated substrate strip.

14. The apparatus of claim 13, wherein the backside stiffening mold comprises a height of about 200 micrometers.

15. The apparatus of claim 13, wherein the laser laminated substrate strip comprises a height of about 200 micrometers.

16. The apparatus of claim 13, wherein the solder balls comprise a diameter of about 10 mils.